

IC Substrate Trends: Market Research Report

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Abstracts

IC substrates, also referred to as IC carriers, are extremely miniaturized circuits used as packaging for ICs, assembled into electronic devices such as digital cameras, mobile phones, engine controls, memory modules, and global positioning systems. In electronic devices including PCs, the mother board comprises a number of components such as GPU, MPU, or memory; which contain a network of IC chips.

The report analyzes and presents an overview of IC Substrates market worldwide. Supported with 3 market data tables, the report provides a review of market trends, growth drivers, and strategic industry activities of major companies worldwide. The report further discusses about various types, and applications of IC Substrates. In addition, 32 companies operating in the IC Substrates arena worldwide including AT & S Austria Technologie & Systemtechnik AG, Camtek Ltd., Compeq Manufacturing Co. Ltd., Founder PCB, Genesem Inc., IBIDEN Co. Ltd., Laird Technologies Inc., QDOS Holdings Bhd., Samsung Electro-Mechanics Co. Ltd., and others are profiled.

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Unimicron Technology and Nan Ya PCB Corporation Develop Coreless IC Substrates

Advanced Semiconductor Engineering to Expand Operations in Taiwan and China

Camtek Unveils Phoenix Range of Automatic Optical Inspection Systems

4. MARKET PARTICIPANTS

AT & S Austria Technologie & Systemtechnik AG (AT&S) (Austria)

Atotech Deutschland GmbH (Germany)

BoardTek Electronics Corporation (Taiwan)

Camtek Ltd. (Israel)

Compeq Manufacturing Co. , Ltd. (Taiwan)

Daeduck Electronics Company (Korea)

DYCONEX AG an MST Company (Switzerland)

Eastern Co. , Ltd. (Japan)

Elec & Eltek International Holdings Ltd. (Singapore)

Founder PCB (China)

Fujitsu Interconnect Technologies Ltd. (Japan)

Genesem, Inc. (Korea)

Hoya Corporation (Japan)

IBIDEN Co. , Ltd. (Japan)

Kinsus Interconnect Technology Corporation (Taiwan)

Kyocera SLC Technologies Corporation (Japan)

Laird Technologies, Inc. (USA)

LG Innotek Co. , Ltd. (Korea)

Linxens (France)

Nan Ya PCB Corporation (Taiwan)

NGK Spark Plug Co. , Ltd. (Japan)

QDOS Holdings Bhd. (Malaysia)

Samsung Electro-Mechanics Co. , Ltd. (South Korea)
SEP Co. , Ltd. (Korea)
Shennan Circuit Co. , Ltd. (China)
Shinko Electric Industries Co. , Ltd. (Japan)
Simmtech Co. , Ltd. (Korea)
Tong Hsing Electronic Industries Ltd. (Taiwan)
Toppan Printing Co. , Ltd. - Material Solutions Division (Japan)
TTM Technologies, Inc. (USA)
Unimicron Technology Corporation (Taiwan)
Zhen Ding Technology Holding Ltd. (China)

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